

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7359258

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TING-YA LO	06/02/2020
CHI-LIN TENG	06/04/2020
HAI-CHING CHEN	06/04/2020
HSIN-YEN HUANG	06/02/2020
SHAU-LIN SHUE	06/04/2020
SHAO-KUAN LEE	06/02/2020
CHENG-CHIN LEE	06/02/2020
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Property Type	Number
Application Number:	17829590
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NAME OF SUBMITTER:	NICOLAS A. SMITH
SIGNATURE:	/Nicolas A. Smith/

PATENT

DATE SIGNED:	06/01/2022
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Total Attachments: 9

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77 (5)

PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):
Ting-Ya Lo

Assignor(s):
Chi-Lin Teng

Assignor(s):
Hai-Ching Chen

Assignor(s):
Hsin-Yen Huang

Assignor(s):
Shau-Lin Shue

Assignor(s):
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Assignor(s):
Cheng-Chin Lee

Assignee:
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Republic of China

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled
"CAPPING LAYER OVERLYING DIELECTRIC STRUCTURE TO INCREASE
RELIABILITY " for which:

a non-provisional application for United States Letters Patent:

was executed on even date preparatory to filing (each inventor should sign this
Assignment on the same day as he/she signs the Declaration); or

was filed on _____ and accorded U.S. Serial No. _____; or

I hereby authorize and request my attorney associated with Customer No. 107476, to insert on the designated lines below the filing date and application number of said application when known:

U.S. Serial No. _____

filed on _____

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for

United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2020.06.02
Date

Ting-Ya, Lo
Name 1st Inventor Ting-Ya Lo

TSMC Docket No. P20193381US00
Docket No. TSMCP1172US

2020/6/4
Date

Chi-Lin Teng
Name 2nd Inventor Chi-Lin Teng

06/04/201
Date

Hai-Ching Chen
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2020.06.02
Date

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TSMC Docket No. P20193381US00
Docket No. TSMCP1172US

2020.06.04
Date


Name 5th Inventor Shau-Lin Shue

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Date

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TSMC Docket No. P20193381US00
Docket No. TSMCP1172US

2020, 6, 2
Date

Cheng-Chin Lee
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